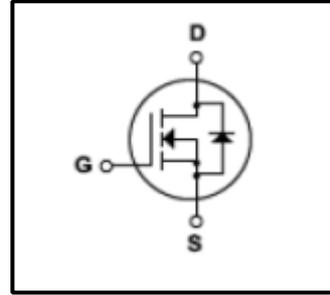


Silicon N-Channel MOSFET

Features

- 12A,650V,RDS(on)(Max0.78Ω)@VGS=10V
- Ultra-low Gate Charge(Typical 51.7nC)
- Fast Switching Capability
- 100%Avalanche Tested
- Maximum Junction Temperature Range(150℃)



General Description

This Power MOSFET is produced using Winsemi's advanced planar stripe, VDMOS technology. This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. This devices is specially well suited for AC-DCswitching power supplies, DC-DCpower converters,high voltage H-bridge motor drive PWM



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
VDSS	Drain Source Voltage	650	V
ID	Continuous Drain Current(@Tc=25℃)	12*	A
	Continuous Drain Current(@Tc=100℃)	7.6*	A
IDM	Drain Current Pulsed (Note1)	48*	A
VGS	Gate to Source Voltage	±30	V
EAS	Single Pulsed Avalanche Energy (Note 2)	990	mJ
EAR	Repetitive Avalanche Energy (Note 1)	22	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
PD	Total Power Dissipation(@Tc=25℃)	51	W
	Derating Factor above 25℃	0.41	W/℃
TJ, Tstg	Junction and Storage Temperature	-55~150	℃
TL	Channel Temperature	300	℃

* Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	Value			Units
		Min	Typ	Max	
RQJC	Thermal Resistance, Junction-to-Case	-	-	2.45	℃/W
RQCS	Thermal Resistance, Case-to-Sink	-	-	-	℃/W
RQJA	Thermal Resistance, Junction-to-Ambient	-	-	62.5	℃/W



Electrical Characteristics (Tc = 25° C)

Characteristics	Symbol	Test Condition	Min	Type	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 30 V, V_{DS} = 0 V$	-	-	± 100	nA
Gate-source breakdown voltage	$V_{(BR)GSS}$	$I_G = \pm 10 \mu A, V_{DS} = 0 V$	± 30	-	-	V
Drain cut-off current	I_{DSS}	$V_{DS} = 650 V, V_{GS} = 0 V$	-	-	10	μA
		$V_{DS} = 480 V, T_c = 125^\circ C$	-	-	100	μA
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 250 \mu A, V_{GS} = 0 V$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10 V, I_D = 250 \mu A$	3	-	4.5	V
Drain-source ON resistance	$R_{DS(ON)}$	$V_{GS} = 10 V, I_D = 6 A$	-	0.64	0.78	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50 V, I_D = 6 A$	-	6.4	-	S
Input capacitance	C_{iss}	$V_{DS} = 25 V,$	-	1830	-	pF
Reverse transfer capacitance	C_{rss}	$V_{GS} = 0 V,$	-	2.2	-	
Output capacitance	C_{oss}	$f = 1 MHz$	-	155	-	
Switching time	Rise time	t_r	-	50	-	ns
	Turn-on time	t_{on}				
	Fall time	t_f				
	Turn-off time	t_{off}				
		$V_{DD} = 325 V,$ $I_D = 12 A$ $R_G = 25 \Omega$ (Note4, 5)				
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} = 520 V,$ $V_{GS} = 10 V,$ $I_D = 12 A$	-	51.7	-	nC
Gate-source charge	Q_{gs}	(Note4,5)	-	9.6	-	
Gate-drain ("miller") Charge	Q_{gd}	(Note4,5)	-	18.6	-	

Source-Drain Ratings and Characteristics (Ta = 25° C)

Characteristics	Symbol	Test Condition	Min	Type	Max	Unit
Continuous drain reverse current	I_{DR}	-	-	-	12	A
Pulse drain reverse current	I_{DRP}	-	-	-	48	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 12 A, V_{GS} = 0 V$	-	-	1.4	V
Reverse recovery time	t_{rr}	$I_{DR} = 12 A, V_{GS} = 0 V,$	-	450	-	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 100 A / \mu s$	-	5.0	-	μC

Note 1.Repeativity rating :pulse width limited by junction temperature

2.L=14mH,IAS=12A,VDD=95V,RG=25Ω,Starting Tj=25°C

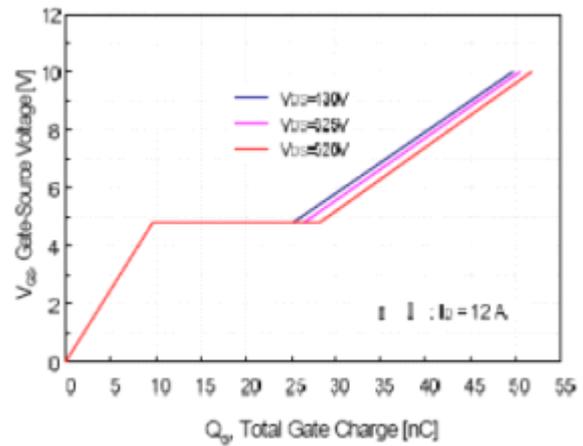
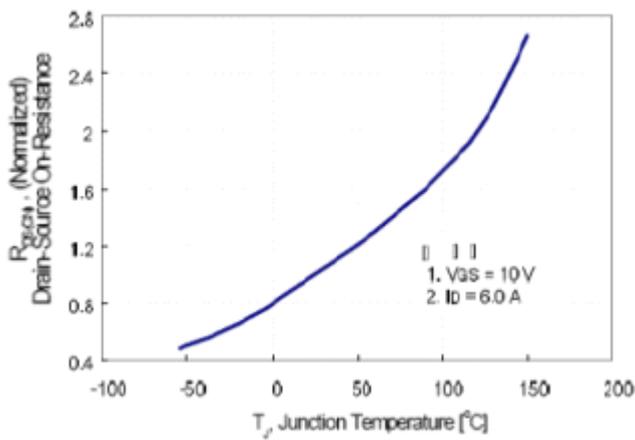
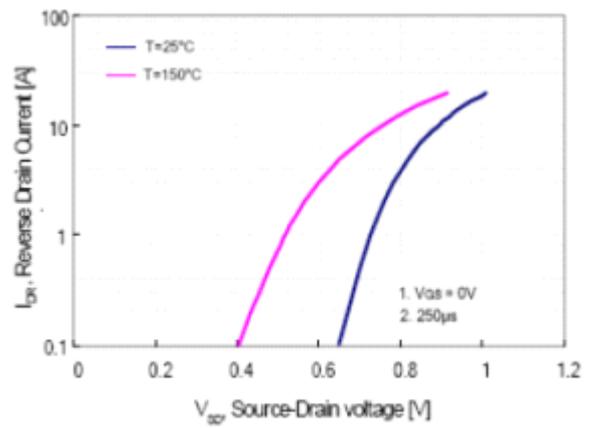
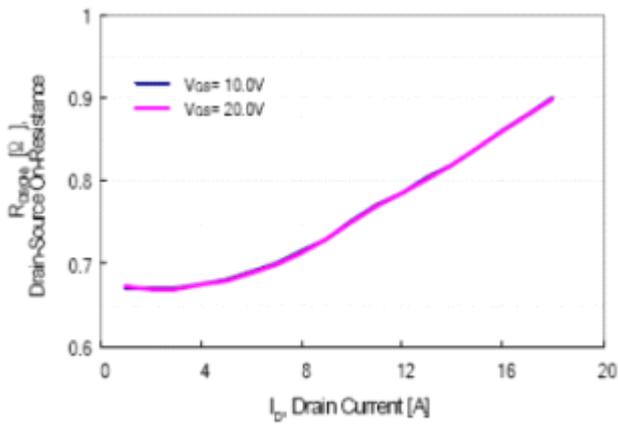
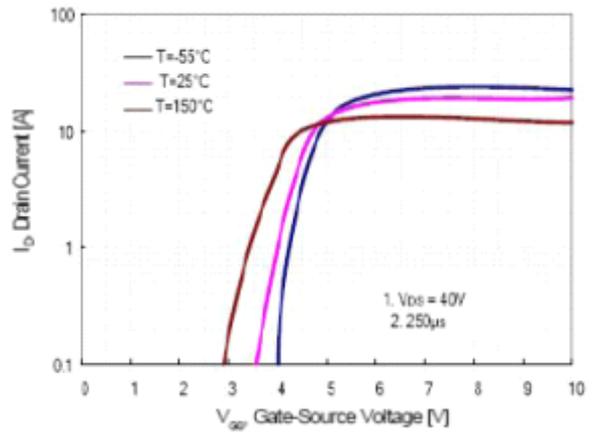
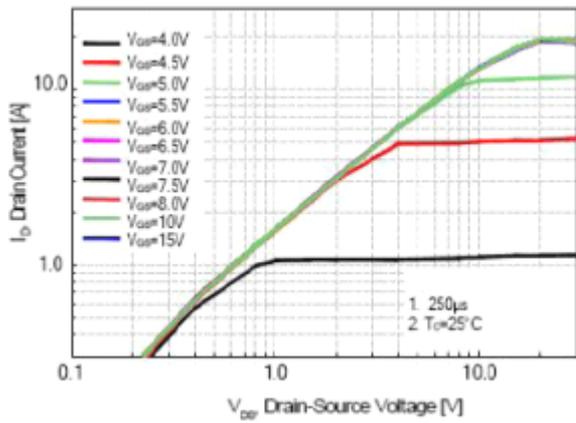
3.Isp≤12A,di/dt≤200A/us, VDD<BV_{DSS},STARTING Tj=25°C

4.Pulse Test: Pulse Width≤300us,Duty Cycles≤2%

5.Essentially independent of operating temperature.

This transistor is an electrostatic sensitive device

Please handle with caution



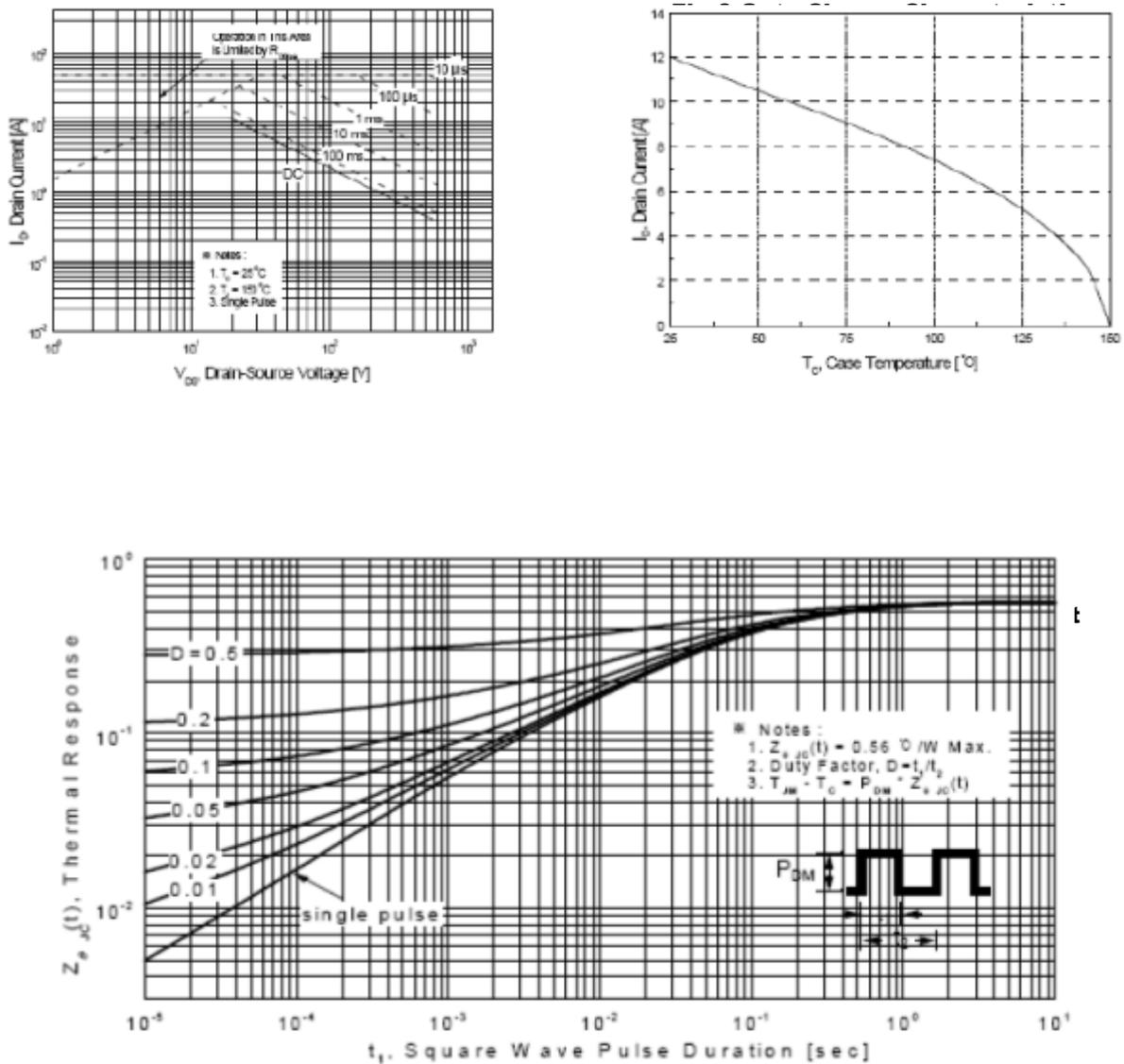


Fig.9 Transient Thermal Response curve

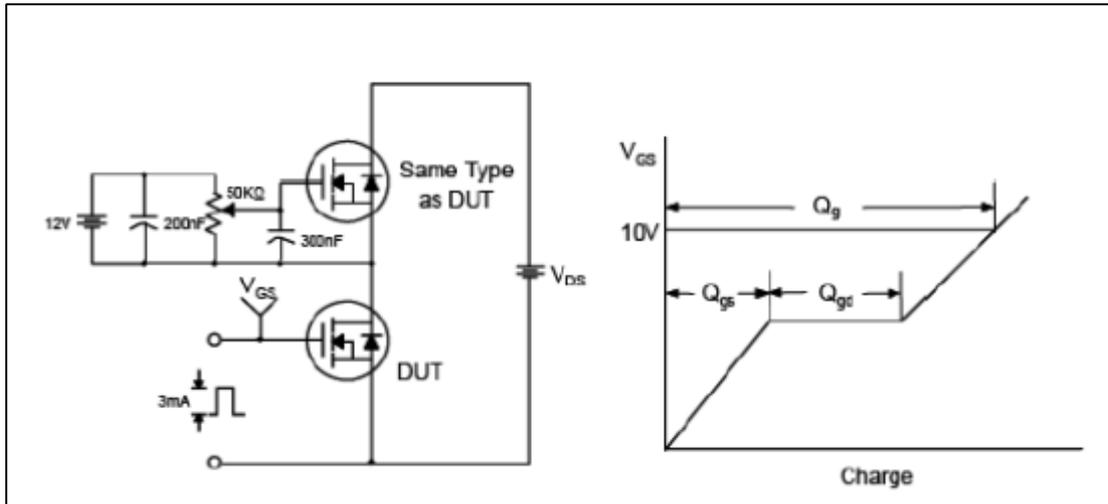


Fig.10 Gate Test circuit & Waveform

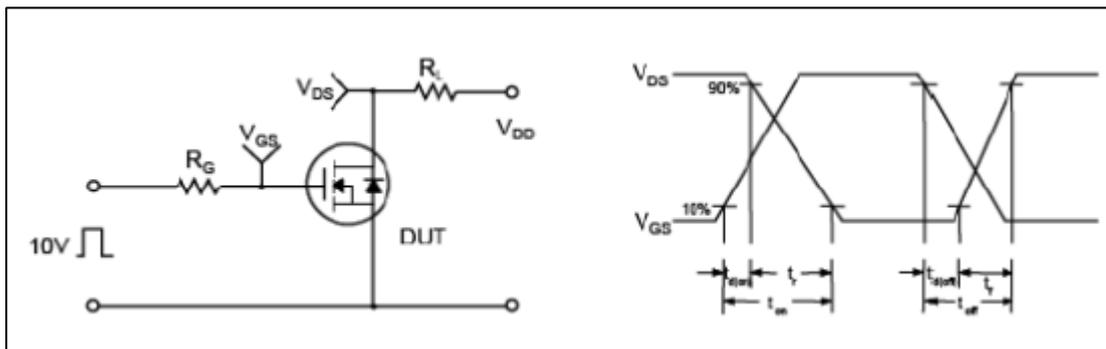


Fig.11 Resistive Switching Test Circuit & Waveform

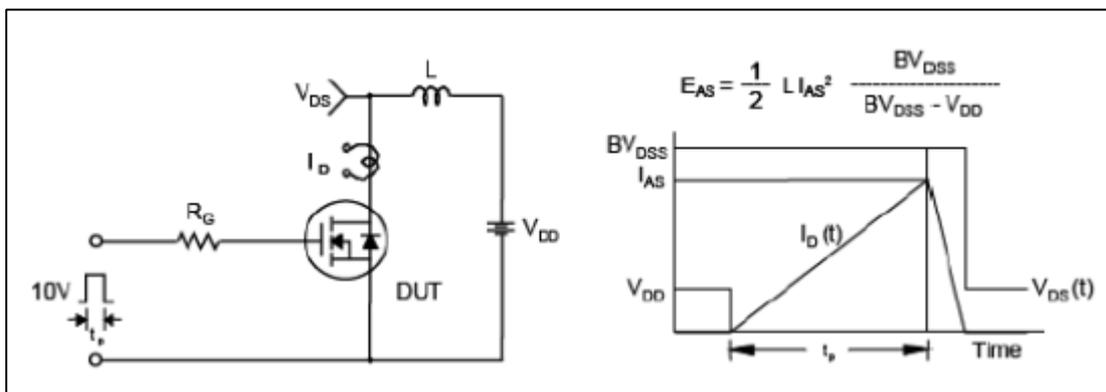


Fig.12 Uncamped Inductive Switching Test Circuit & Waveform

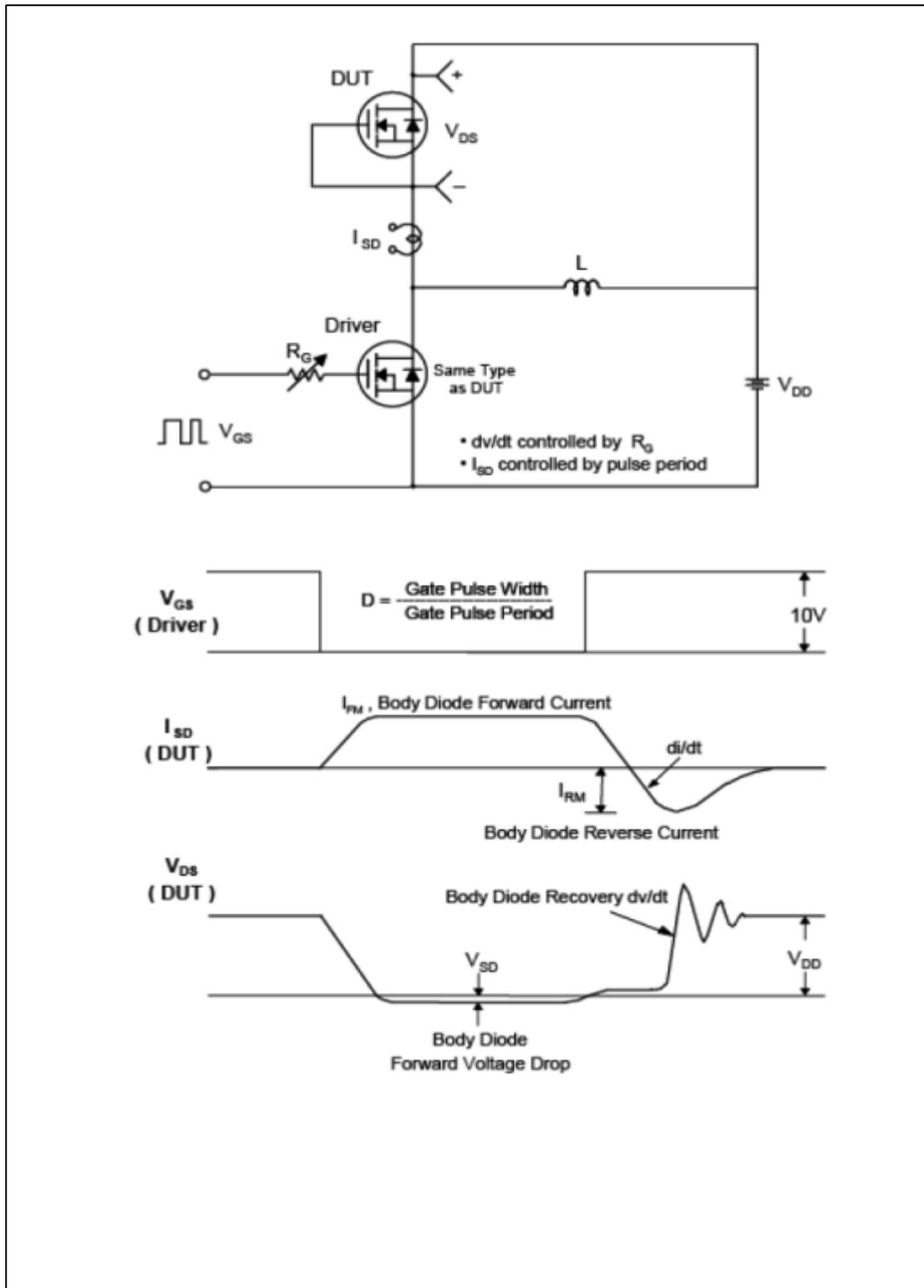


Fig.13 Peak Diode Recovery dv/dt Test Circuit & Waveform

TO-220 Package Dimension

